

N-CHANNEL SILICON POWER MOS-FET

FAP-II SERIES

■ Features

- High speed switching
- Low on-resistance
- No secondary breakdown
- Low driving power
- High voltage
- $V_{GS} = \pm 30V$ Guarantee
- Avalanche-proof

■ Applications

- Switching regulators
- UPS
- DC-DC converters
- General purpose power amplifier

■ Max. Ratings and Characteristics

● Absolute Maximum Ratings($T_c = 25^\circ C$) :

Items	Symbols	Ratings	Units
Drain-source voltage	V_{DSS}	500	V
Continuous drain current	I_D	10	A
Pulsed drain current	$I_{D(puls)}$	30	A
Continuous reverse drain current	I_{DR}	10	A
Gate-source peak voltage	V_{GS}	± 30	V
Max. power dissipation	P_D	50	W
Operating and storage temperature range	T_{ch}	150	$^\circ C$
	T_{stg}	-55 ~ +150	$^\circ C$

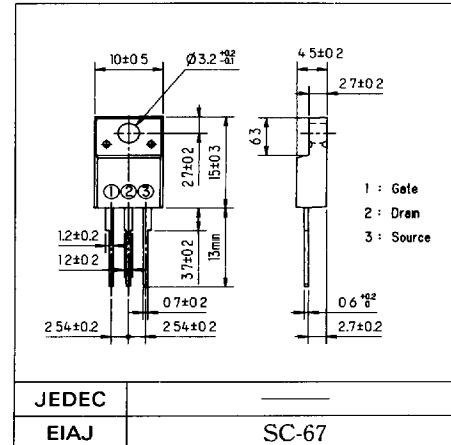
● Electrical Characteristics($T_c = 25^\circ C$)

Items	Symbols	Test Conditions	Min.	Typ.	Max.	Units
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 1mA \quad V_{GS} = 0V$	500			V
Gate threshold voltage	$V_{GS(th)}$	$I_D = 1mA \quad V_{DS} = V_{GS}$	2.5	3.5	5.0	V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 500V \quad T_{ch} = 25^\circ C$ $V_{GS} = 0V \quad T_{ch} = 125^\circ C$		10	500	μA
Gate-source leakage current	I_{GS}	$V_{GS} = \pm 30V \quad V_{DS} = 0V$		0.2	1.0	mA
Drain-source on-state resistance	$R_{DS(on)}$	$I_D = 5A \quad V_{GS} = 10V$		0.7	0.9	Ω
Forward transconductance	g_{fs}	$I_D = 5A \quad V_{DS} = 25V$	4.0	6.5		S
Input capacitance	C_{iss}	$V_{DS} = 25V$		1200	1800	pF
Output capacitance	C_{oss}	$V_{GS} = 0V$		160	240	
Reverse transfer capacitance	C_{rss}	$f = 1MHz$		70	100	
Turn-on time t_{on} ($t_{on} + t_{d(on)} + t_f$)	$t_{d(on)}$ t_r	$V_{CC} = 300V \quad I_D = 10A$	30	45		ns
Turn-off time t_{off} ($t_{d(off)} + t_f$)	$t_{d(off)}$ t_f	$V_{GS} = 10V$	80	120		
Diode forward on-voltage	V_{SD}	$I_F = 2 \times I_{DR} \quad V_{GS} = 0V \quad T_{ch} = 25^\circ C$	160	240		
Reverse recovery time	t_{rr}	$I_F = I_{DR} \quad d_i/d_t = 100A/\mu s \quad T_{ch} = 25^\circ C$	80	120		
			1.10	1.5		V
			500			ns

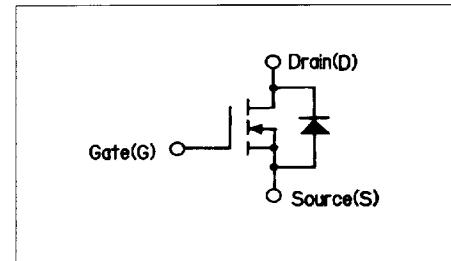
● Thermal Characteristics

Items	Symbols	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance	$R_{th(ch-a)}$	channel to air			62.5	$^\circ C/W$
	$R_{th(ch-c)}$	channel to case			2.5	$^\circ C/W$

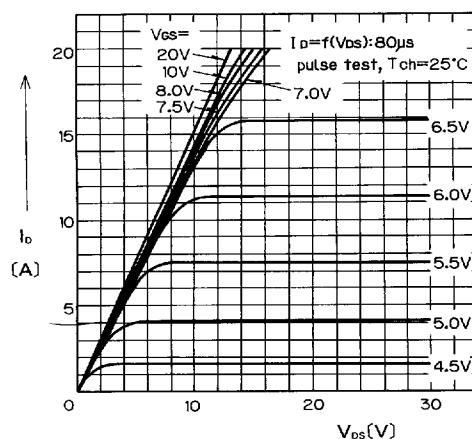
■ Outline Drawings



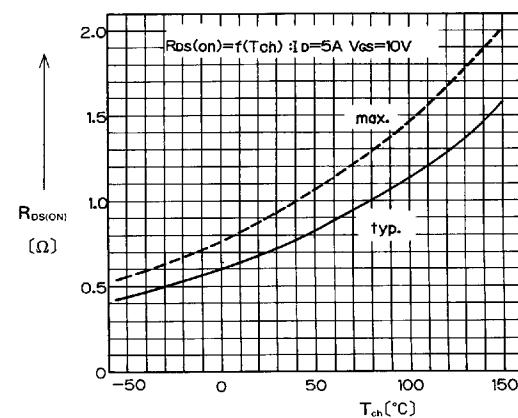
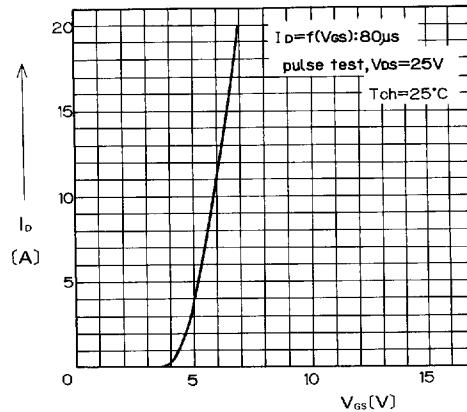
■ Equivalent Circuit Schematic



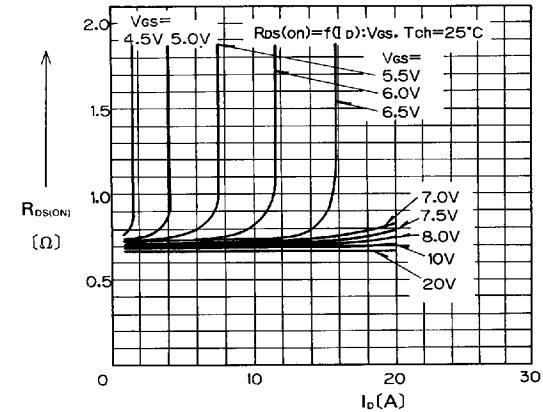
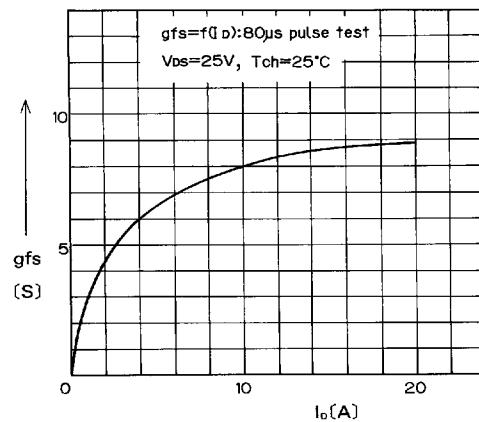
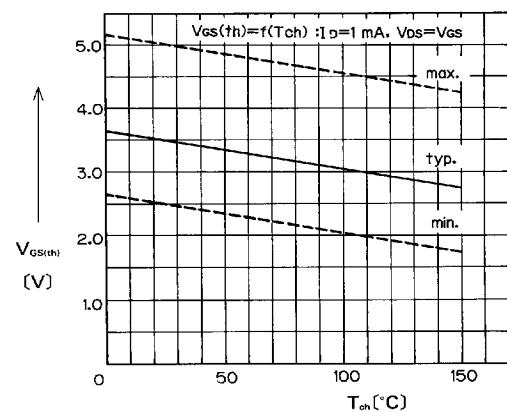
■ Characteristics

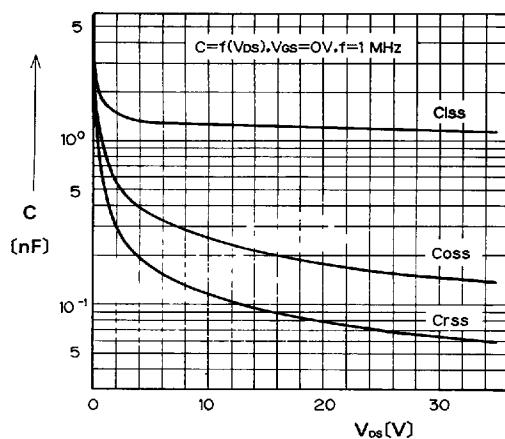
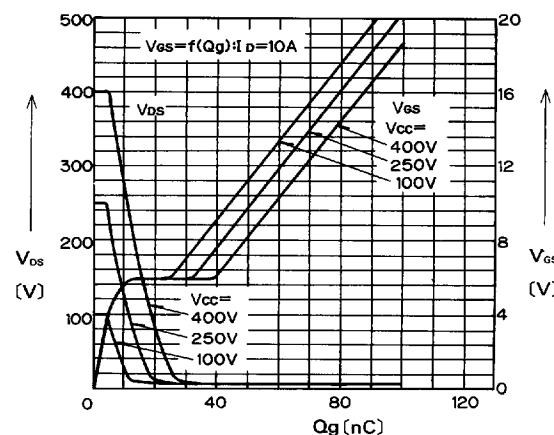


Typical Output Characteristics

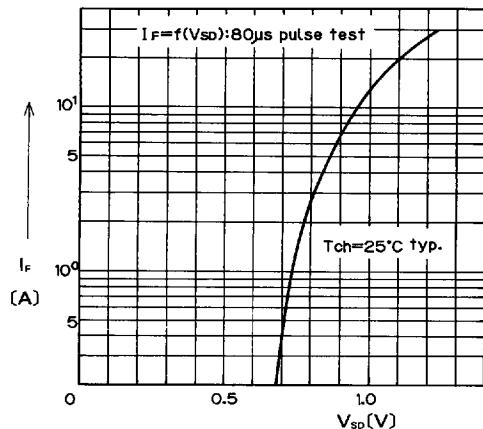
On State Resistance vs. T_{ch} 

Typical Transfer Characteristics

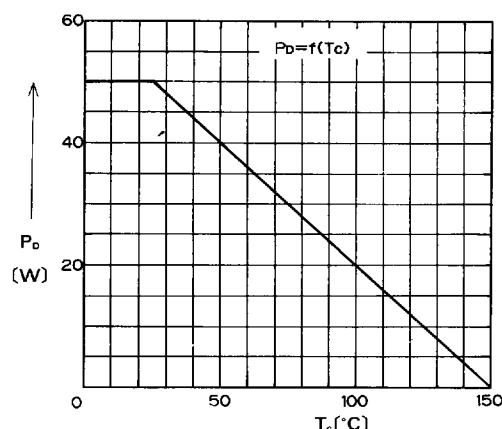
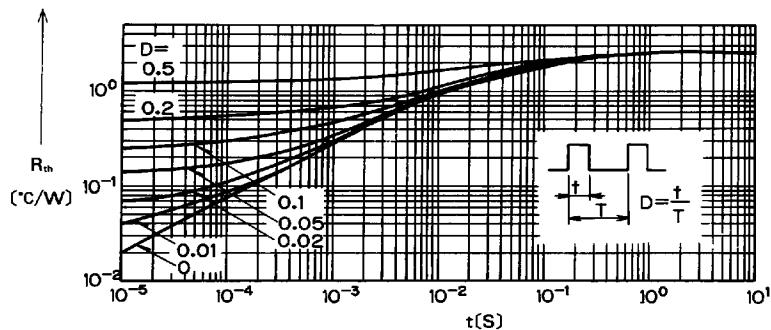
Typical Drain-Source on State Resistance vs. I_o Typical Forward Transconductance vs. I_o Gate Threshold Voltage vs. T_{ch}

Typical Capacitance vs. V_{ds} 

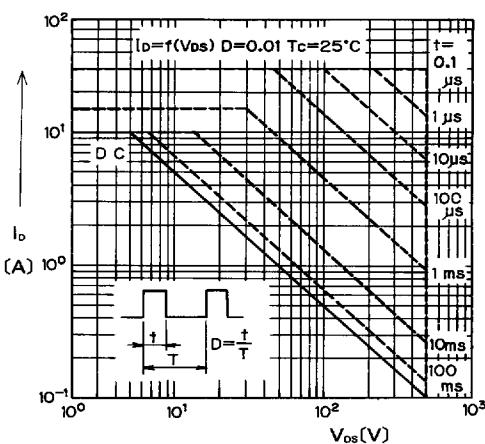
Typical Input Charge



Forward Characteristic of Reverse Diode

Allowable Power Dissipation vs. T_c 

Transient Thermal Impedance



Safe Operating Area